

Customer Information Notification Update

202108019IU01: i.MX 8M Plus Consumer and Industrial Datasheet

Update to Rev.2

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 02, 2023 Effective date: Apr 03, 2023 Management summary Industrial and Consumer Datasheet (DS) update for i.MX 8M Plus to revision 2. **Change Category** □ Wafer □ ☐ Test ☐ Design Product Marking Assembly Fab **Process Process** Process □ Wafer □ ☐ Test ☐ Mechanical ☐ Errata Assembly Fab Materials Specification Equipment Materials □ Wafer □ Electrical ☐ Test Assembly Packing/Shipping/Labeling Fab spec./Test Location Location

PCN Overview

Other: datasheet

Description

Location

Firmware

NXP Semiconductors announces Industrial and Consumer Datasheet (DS) update for i.MX 8M Plus to revision 2. The revision history included in the updated document provides a detailed description of the changes.

coverage

Highlighted Changes:

- Updated the Figure 2, "Part number nomenclature—i.MX 8M Plus family of processors"
- Updated IPP DO CLKO1, IPP DO CLKO2, GIC CLK ROOT, MAIN AXI CLK ROOT,

WRCLK CLK ROOT and MEMREPAIR in the Table 13, "Maximum frequency of modules"

- Updated Figure 44, "FlexSPI output timing in SDR mode"
- In Table 21, "Chip power in different LP mode" added SNVS mode
- For VIDEO_PLL1, changed the value from '650 1190 MHz' to '325-650 MHz' in the Table 25, "PLL electrical parameters".
- Updated the footnotes in Table 65, "Master mode SAI timing (50 MHz)" and Table 67, "Slave mode SAI timing (50 MHz)".
- Added text "Level shifters are... by HDMI interface" in Section 3.8.8, HDMI Tx module parameters.

The i.MX 8M Plus Industrial and Consumer Datasheet Rev.2 are attached to this notice, and can be found at:

https://www.nxp.com/webapp/Download?colCode=IMX8MPIEC

https://www.nxp.com/webapp/Download?colCode=IMX8MPCEC

Reason

Datasheet has been updated to correct errors and provide additional technical clarification on some device features. Added new Part number nomenclature.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: view online

Update Information

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Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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